



512Kx8 MONOLITHIC SRAM

FEATURES

- Access Times 15, 17, 20ns
- Revolutionary, Center Power/Ground Pinout JEDEC Approved
 - 36 lead Ceramic SOJ (Package 100)
 - 36 lead Ceramic Flat Pack (Package 226)
- Evolutionary, Corner Power/Ground Pinout JEDEC Approved
 - 32 pin Ceramic DIP (Package 300)
 - 32 lead Ceramic SOJ (Package 101)
 - 32 lead Ceramic Thinpack™ Flat Pack (Package 321)
- 32 pin, Rectangular Ceramic Leadless Chip Carrier (Package 601)
- Low Power CMOS
- Low Voltage Operation
 - 3.3V ± 10% Power Supply
- Commercial, Industrial and Military Temperature Range
- TTL Compatible Inputs and Outputs
- Fully Static Operation:
 - No clock or refresh required
- Three State Output

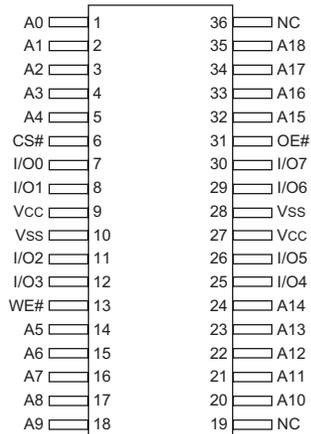
* This product is subject to change without notice.

REVOLUTIONARY PINOUT

EVOLUTIONARY PINOUT

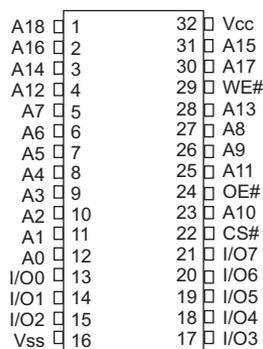
36 FLAT PACK
36 CSOJ

TOP VIEW



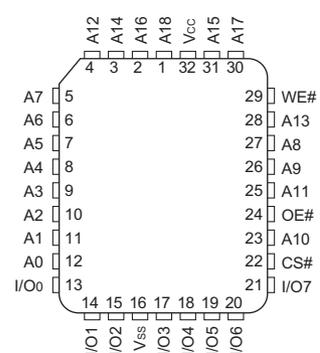
32 DIP
32 CSOJ (DE)
32 FLAT PACK (FF)

TOP VIEW



32 CLCC

TOP VIEW



PIN DESCRIPTION

A0-18	Address Inputs
I/O 0-7	Data Input/Output
CS#	Chip Select
OE#	Output Enable
WE#	Write Enable
Vcc	Power Supply
Vss	Ground



ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Min	Max	Unit
Operating Temperature	T _A	-55	+125	°C
Storage Temperature	T _{STG}	-65	+150	°C
Signal Voltage Range to GND	V _G	-0.5	4.6	V
Junction Temperature	T _J		150	°C
Supply Voltage	V _{CC}	-0.5	4.6	V

TRUTH TABLE

CS#	OE#	WE#	MODE	DATA I/O	POWER
H	X	X	Standby	High Z	Standby
L	L	H	Read	Data Out	Active
L	X	L	Write	Data In	Active
L	H	H	Out Disable	High Z	Active

RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Min	Max	Unit
Supply Voltage	V _{CC}	3.0	3.6	V
Input High Voltage	V _{IH}	2.2	V _{CC} + 0.3	V
Input Low Voltage	V _{IL}	-0.3	+0.8	V
Operating Temp. (Mil)	T _A	-55	+125	°C

CAPACITANCE

T_A = +25°C

Parameter	Symbol	Conditions	Max	Unit
Input capacitance	C _{IN}	V _{IN} = 0 V, f = 1.0 MHz	12	pF
Output capacitance	C _{OUT}	V _{OUT} = 0 V, f = 1.0 MHz	12	pF

This parameter is guaranteed by design but not tested.

DC CHARACTERISTICS - CMOS COMPATIBLE

V_{CC} = 5.0V, GND = 0V, -55°C ≤ T_A ≤ 125°C

Parameter	Symbol	Conditions	Min	Max	Unit
Input Leakage Current	I _{LI}	V _{CC} = 3.6, V _{IN} = GND to V _{CC}		10	μA
Output Leakage Current	I _{LO}	CS# = V _{IH} , OE# = V _{IH} , V _{OUT} = GND to V _{CC}		10	μA
Operating Supply Current	I _{CC}	CS# = V _{IH} , OE# = V _{IH} , f = 5MHz, V _{CC} = 3.6		100	mA
Standby Current	I _{SS}	CS# = V _{IH} , OE# = V _{IH} , f = 5MHz, V _{CC} = 3.6		50	mA
Output Low Voltage	V _{OL}	I _{OL} = 4.0mA		0.4	V
Output High Voltage	V _{OH}	I _{OH} = -4.0mA	2.4		V



AC CHARACTERISTICS

V_{CC} = 5.0V, GND = 0V, -55°C ≤ T_A ≤ 125°C

Parameter Read Cycle	Symbol	-15		-17		-20		Unit
		Min	Max	Min	Max	Min	Max	
Read Cycle Time	t _{RC}	15		17		20		ns
Address Access Time	t _{AA}		15		17		20	ns
Output Hold from Address Change	t _{OH}	0		0		0		ns
Chip Select Access Time	t _{ACS}		15		17		20	ns
Output Enable to Output Valid	t _{OE}		8		8		10	ns
Chip Select to Output in Low Z	t _{CLZ1}	1		1		1		ns
Output Enable to Output in Low Z	t _{OLZ1}	0		0		0		ns
Chip Disable to Output in High Z	t _{CHZ1}		8		8		10	ns
Output Disable to Output in High Z	t _{OHZ1}		8		8		10	ns

1. This parameter is guaranteed by design but not tested.

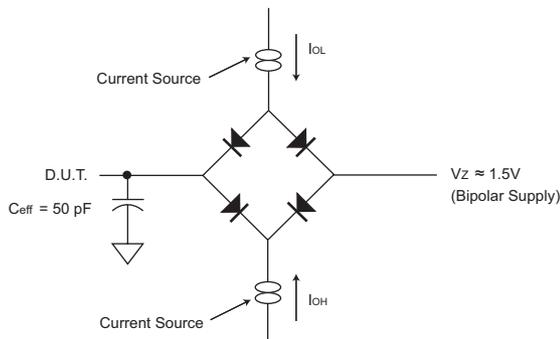
AC CHARACTERISTICS

V_{CC} = 5.0V, GND = 0V, -55°C ≤ T_A ≤ 125°C

Parameter Write Cycle	Symbol	-15		-17		-20		Unit
		Min	Max	Min	Max	Min	Max	
Write Cycle Time	t _{WC}	15		17		20		ns
Chip Select to End of Write	t _{CW}	12		12		14		ns
Address Valid to End of Write	t _{AW}	12		12		14		ns
Data Valid to End of Write	t _{DW}	9		9		10		ns
Write Pulse Width	t _{WP}	12		14		14		ns
Address Setup Time	t _{AS}	0		0		0		ns
Address Hold Time	t _{AH}	0		0		0		ns
Output Active from End of Write	t _{OW1}	2		3		3		ns
Write Enable to Output in High Z	t _{WHZ1}		8		8		9	ns
Data Hold Time	t _{DH}	0		0		0		ns

1. This parameter is guaranteed by design but not tested.

AC TEST CIRCUIT



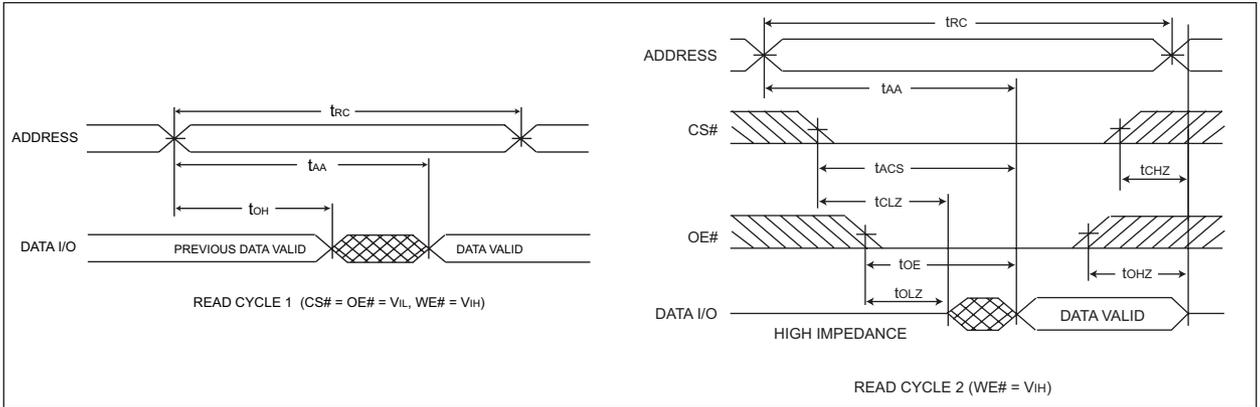
AC TEST CONDITIONS

Parameter	Typ	Unit
Input Pulse Levels	V _{IL} = 0, V _{IH} = 2.5	V
Input Rise and Fall	5	ns
Input and Output Reference Level	1.5	V
Output Timing Reference Level	1.5	V

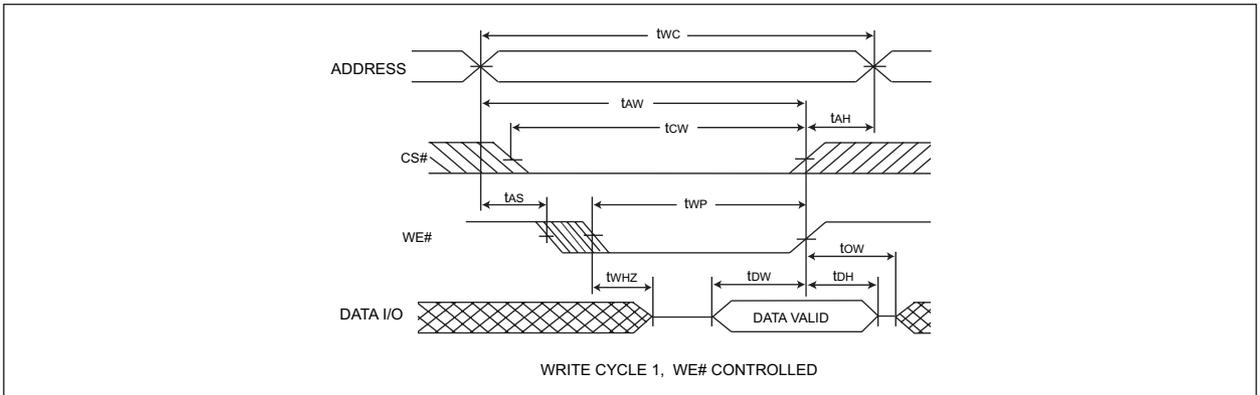
Notes:
V_Z is programmable from -2V to +7V.
I_{OL} & I_{OH} programmable from 0 to 16mA.
Tester Impedance Z₀ = 75Ω.
V_Z is typically the midpoint of V_{OH} and V_{OL}.
I_{OL} & I_{OH} are adjusted to simulate a typical resistive load circuit.
ATE tester includes jig capacitance.



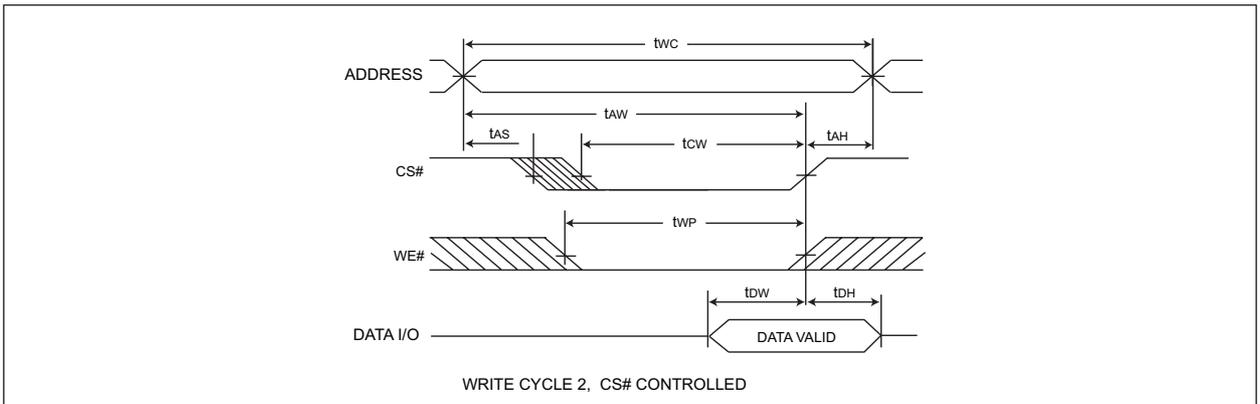
TIMING WAVEFORM - READ CYCLE



WRITE CYCLE - WE# CONTROLLED

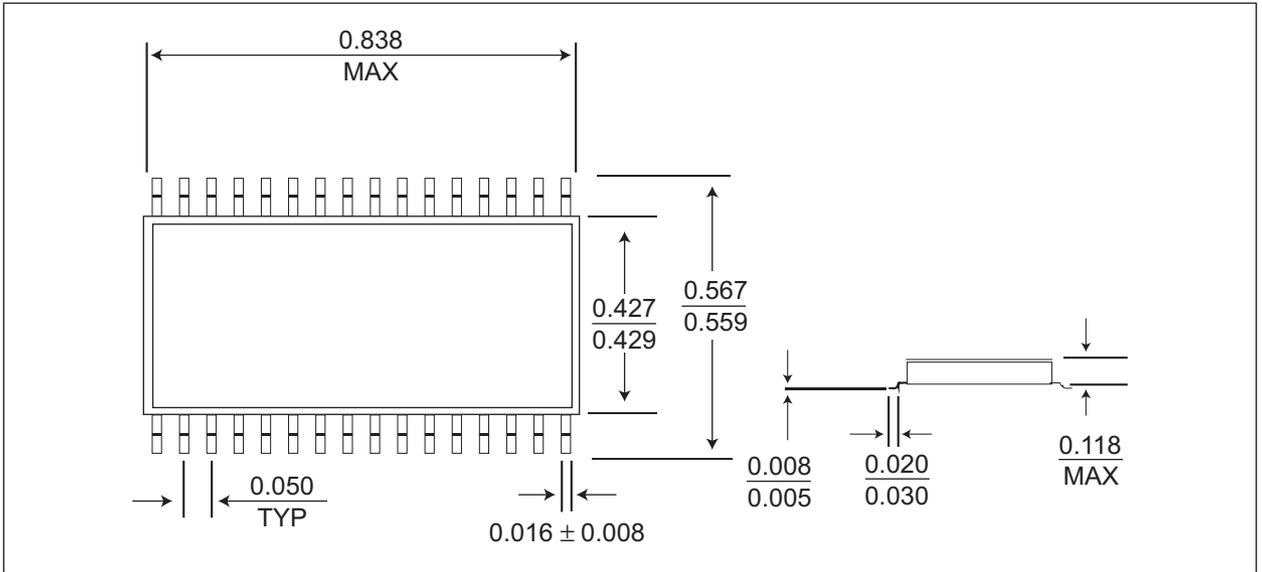


WRITE CYCLE - CS# CONTROLLED



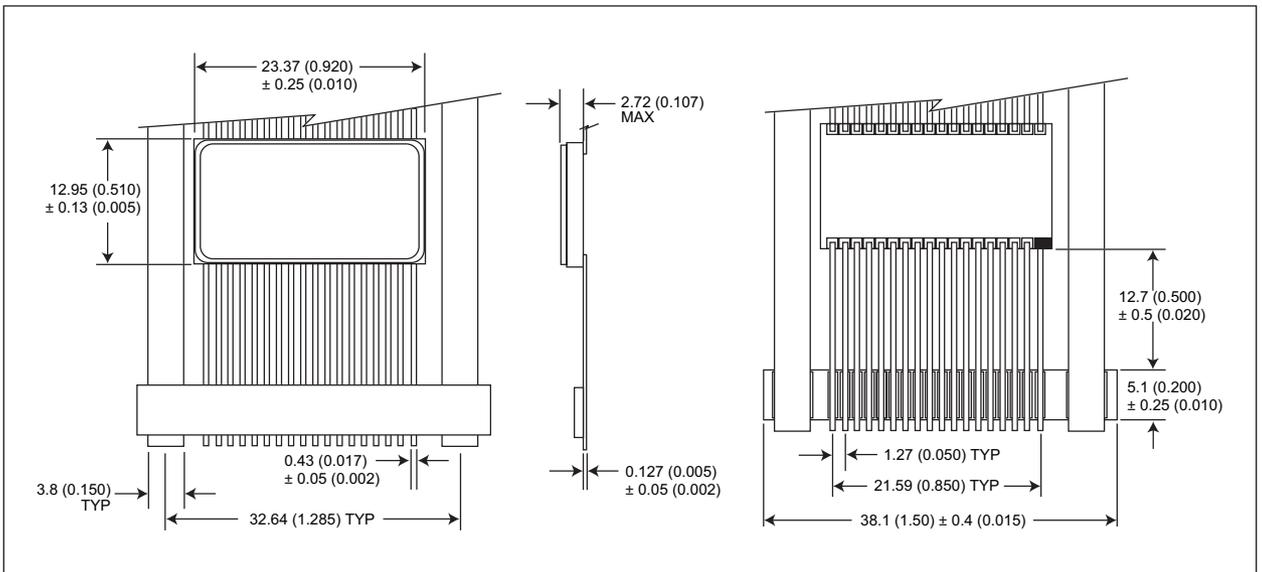


PACKAGE 321: 32 PIN CERAMIC THINPACK™ FLATPACK



ALL LINEAR DIMENSIONS ARE MILLIMETERS AND PARENTHETICALLY IN INCHES

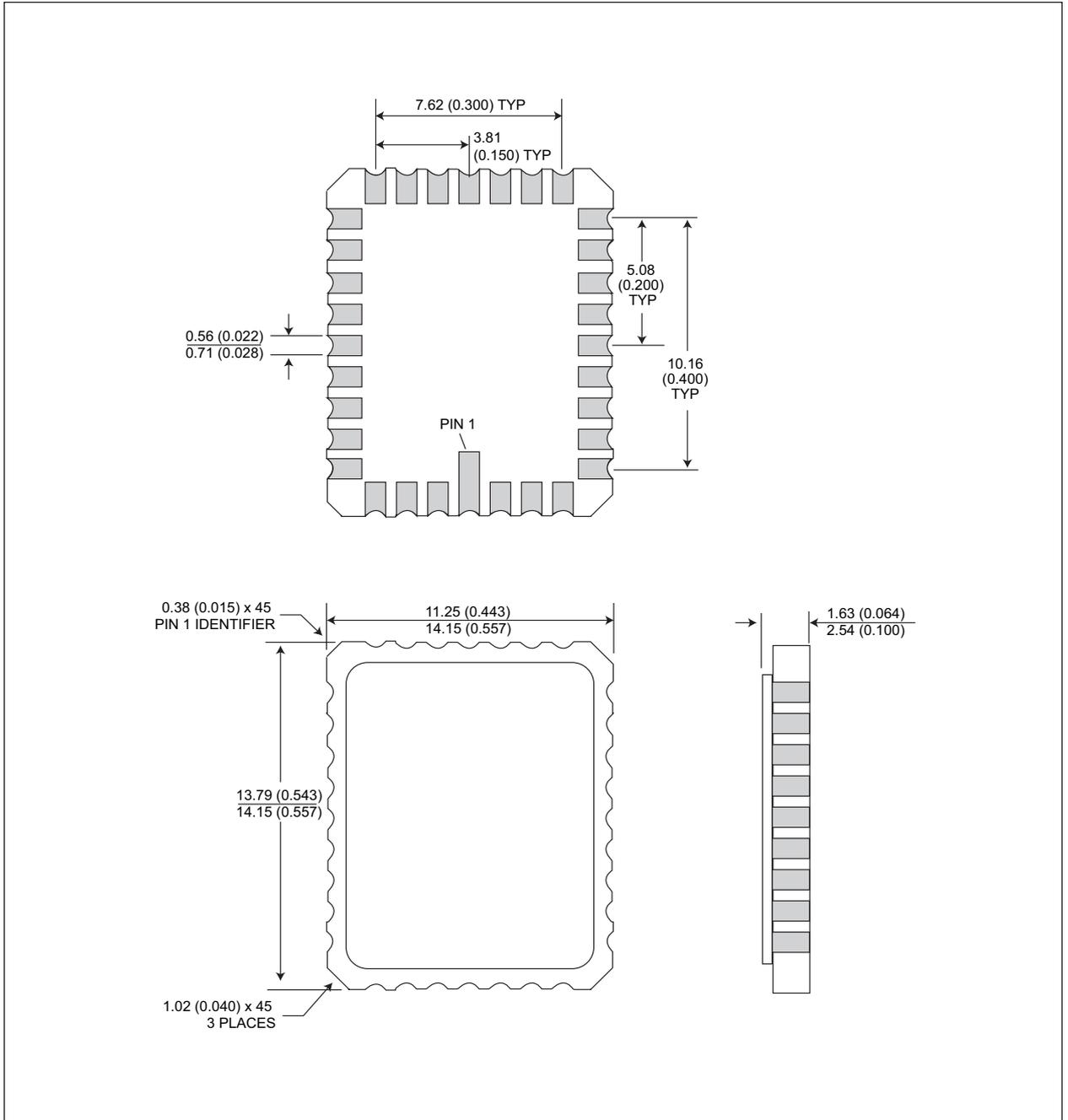
PACKAGE 226: 36 LEAD, CERAMIC FLAT PACK



ALL LINEAR DIMENSIONS ARE MILLIMETERS AND PARENTHETICALLY IN INCHES



PACKAGE 601: 32 PIN, RECTANGULAR CERAMIC LEADLESS CHIP CARRIER



ALL LINEAR DIMENSIONS ARE MILLIMETERS AND PARENTHETICALLY IN INCHES



ORDERING INFORMATION

W M S 512K 8 V - XXX X X X

WHITE ELECTRONIC DESIGNS CORP. _____

MONOLITHIC _____

SRAM _____

ORGANIZATION, 512K x 8 _____

LOW VOLTAGE SUPPLY 3.3V ± 10% _____

ACCESS TIME (ns) _____

PACKAGE: _____

- C = 32 pin Ceramic 0.600" DIP (Package 300)
- CL = 32 pin Rectangular Ceramic Leadless Chip Carrier (Package 601)
- DE = 32 Lead Ceramic SOJ (Package 101) Evolutionary
- DJ = 36 Lead Ceramic SOJ (Package 100)
- F = 36 Lead Ceramic Flat Pack (Package 226)
- FF = 32 Lead Ceramic Thinpack™ Flat Pack (Package 321)

DEVICE GRADE: _____

- M = Military Screened -55°C ≤ T_A ≤ 125°C
- I = Industrial -40°C ≤ T_A ≤ 85°C
- C = Commercial 0°C ≤ T_A ≤ 70°C

LEAD FINISH: _____

- Blank = Gold plated leads
- A = Solder dip leads